TENTATIVE TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π-MOS V)

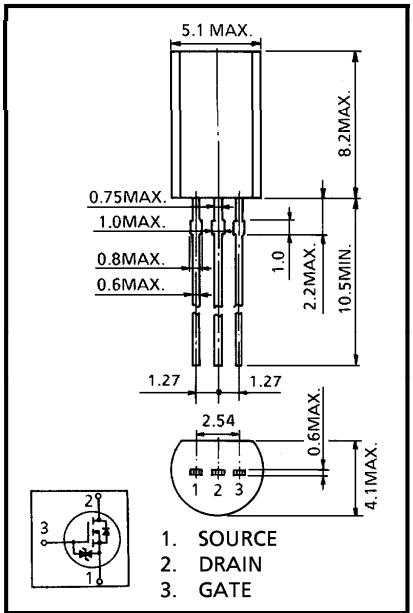
2SK2998

HIGH SPEED, HIGH VOLTAGE SWITCHING APPLICATIONS

CHOPPER REGULATOR, DC-DC CONVERTER APPLICATIONS

INDUSTRIAL APPLICATIONS

Unit in mm



JEDEC	TO-92MOD
EIAJ	—
TOSHIBA	2-5J1C

Weight : 0.36g (Typ.)

- Low Drain-Source ON Resistance : $R_{DS\,(ON)}=11.5\Omega$ (Typ.)
- High Forward Transfer Admittance : $|Y_{fs}|=0.4S$ (Typ.)
- Low Leakage Current : $I_{DSS}=100\mu A$ (Max.) ($V_{DS}=500V$)
- Enhancement-Mode : $V_{th}=2.0\sim4.0V$ ($V_{DS}=10V$, $I_D=1mA$)

MAXIMUM RATINGS (Ta = 25°C)

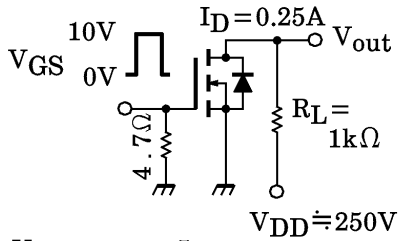
CHARACTERISTIC		SYMBOL	RATING	UNIT
Drain-Source Voltage		V_{DSS}	500	V
Drain-Gate Voltage ($R_{GS}=20k\Omega$)		V_{DGR}	500	V
Gate-Source Voltage		V_{GSS}	±30	V
Drain Current	DC	I_D	0.5	A
	Pulse	I_{DP}	1.5	A
Drain Power Dissipation (Ta=25°C)		P_D	0.9	W
Channel Temperature		T_{ch}	150	°C
Storage Temperature Range		T_{stg}	−55~150	°C

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Ambient	$R_{th\,(ch-a)}$	138	°C / W

This transistor is an electrostatic sensitive device.
Please handle with caution.

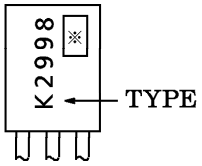
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		I_{GSS}	$V_{GS}=\pm25V$, $V_{DS}=0V$	—	—	±10	μA
Gate-Source Breakdown Voltage		$V_{(BR)\,GSS}$	$I_D=\pm10mA$, $V_{GS}=0V$	±30	—	—	V
Drain Cut-off Current		I_{DSS}	$V_{DS}=500V$, $V_{GS}=0V$	—	—	100	μA
Drain-Source Breakdown Voltage		$V_{(BR)\,DSS}$	$I_D=10mA$, $V_{GS}=0V$	500	—	—	V
Gate Threshold Voltage		V_{th}	$V_{DS}=10V$, $I_D=1mA$	2.0	—	4.0	V
Drain-Source ON Resistance		$R_{DS\,(ON)}$	$V_{GS}=10V$, $I_D=0.25A$	—	11.5	18	Ω
Forward Transfer Admittance		$\|Y_{fs}\|$	$V_{DS}=10V$, $I_D=0.25A$	0.2	0.4	—	S
Input Capacitance		C_{iss}	$V_{DS}=10V$, $V_{GS}=0V$, $f=1MHz$	—	75	—	pF
Reverse Transfer Capacitance		C_{rss}		—	7	—	
Output Capacitance		C_{oss}		—	25	—	
Switching Time	Rise Time	t_r	 V_{IN} : t_r, $t_f<5ns$, Duty ≦ 1%, $t_w=10\mu s$	—	11	—	ns
	Turn-on Time	t_{on}		—	18	—	
	Fall Time	t_f		—	54	—	
	Turn-off Time	t_{off}		—	95	—	
Total Gate Charge (Gate-Source Plus Gate-Drain)		Q_g	$V_{DD}\fallingdotseq400V$, $V_{GS}=10V$, $I_D=0.5A$	—	3.8	—	nC
Gate-Source Charge		Q_{gs}		—	1.9	—	
Gate-Drain ("Miller") Charge		Q_{gd}		—	1.9	—	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	I_{DR}	—	—	—	0.5	A
Pulse Drain Reverse Current	I_{DRP}	—	—	—	1.5	A
Diode Forward Voltage	V_{DSF}	$I_{DR}=0.5A$, $V_{GS}=0V$	—	—	−1.7	V
Reverse Recovery Time	t_{rr}	$I_{DR}=0.5A$, $V_{GS}=0V$	—	190	—	ns
Reverse Recovery Charge	Q_{rr}	$dI_{DR}/dt=100A/\mu s$	—	380	—	nC

MARKING

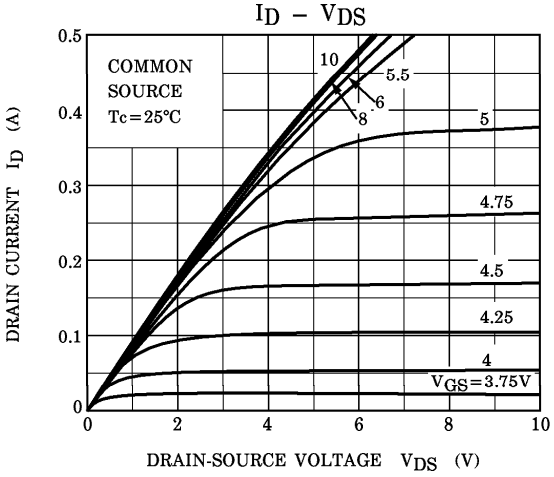


※ Lot Number

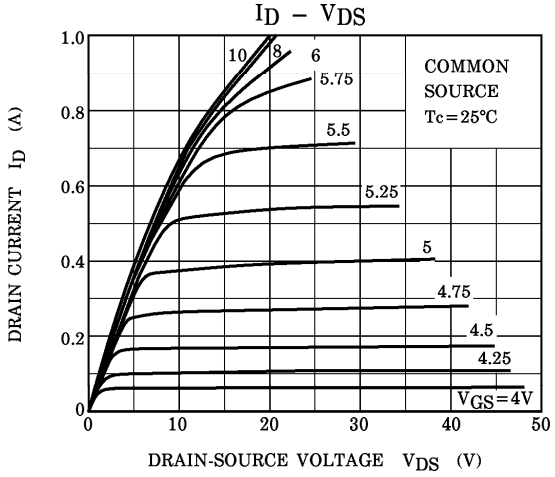
□□ — Month (Starting from Alphabet A)

— Year (Last Number of the Christian Era)

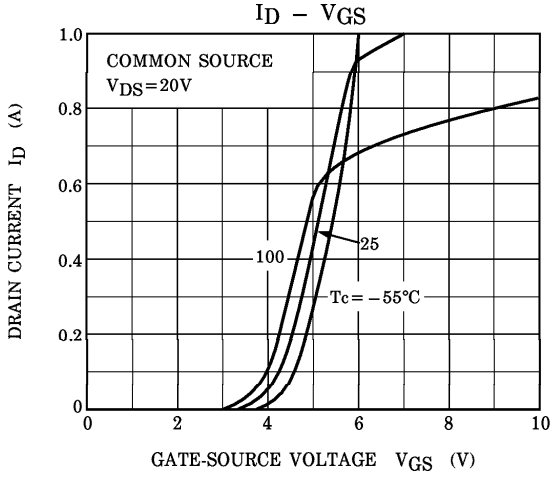
$I_D - V_{DS}$



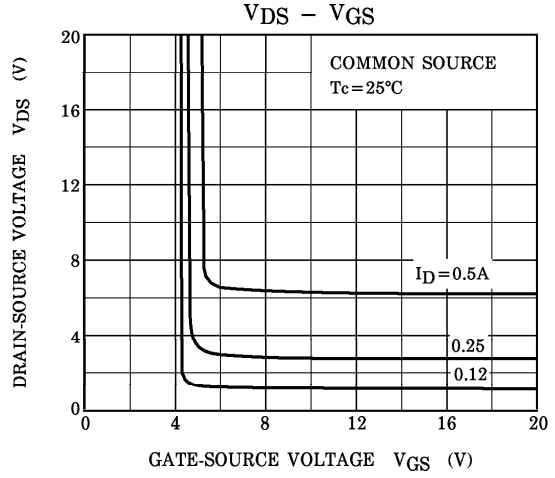
$I_D - V_{DS}$



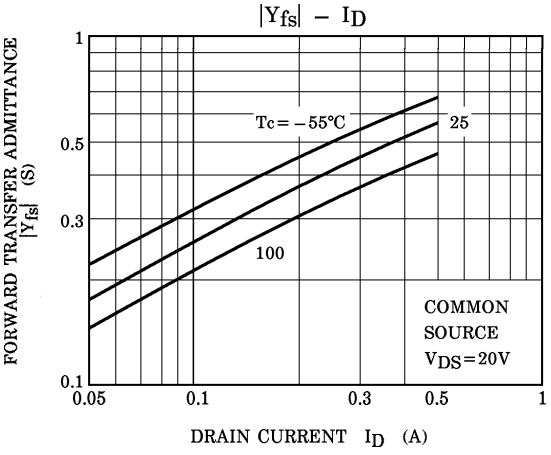
$I_D - V_{GS}$



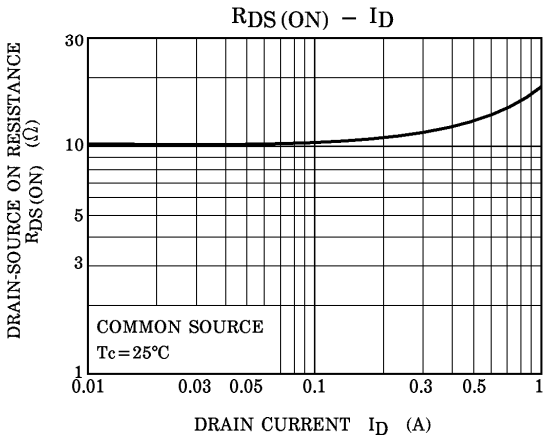
$V_{DS} - V_{GS}$



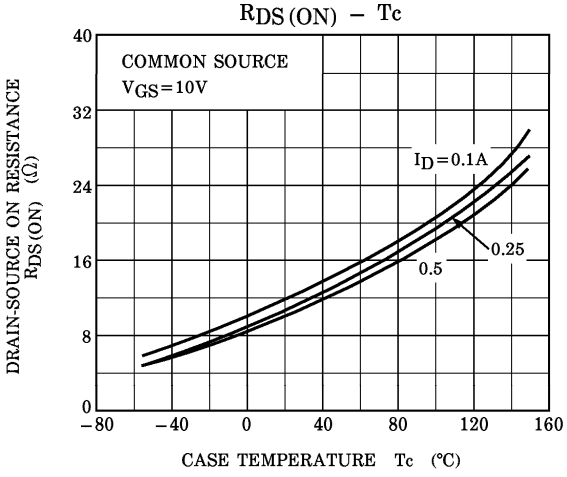
$|Y_{fs}| - I_D$



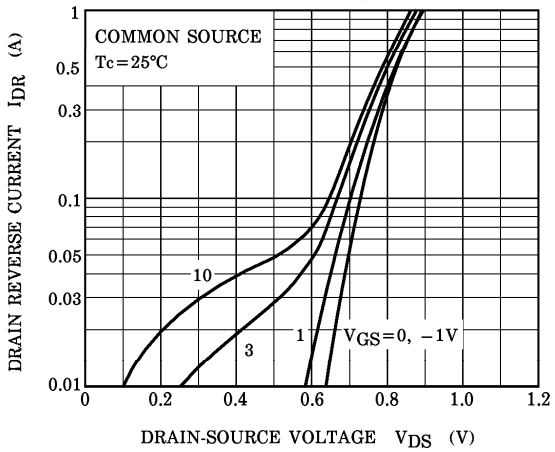
$R_{DS\,(ON)} - I_D$



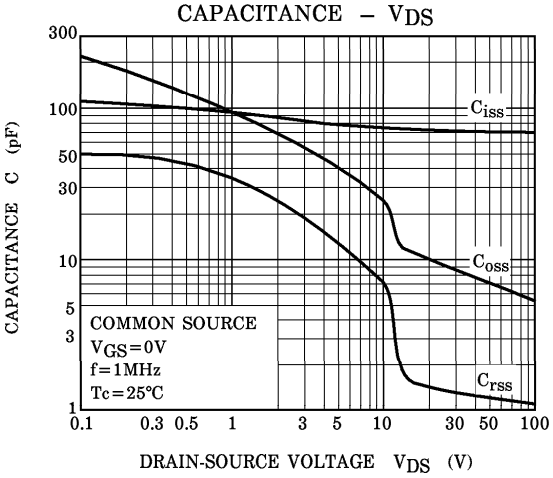
$R_{DS\,(ON)}$ – Tc



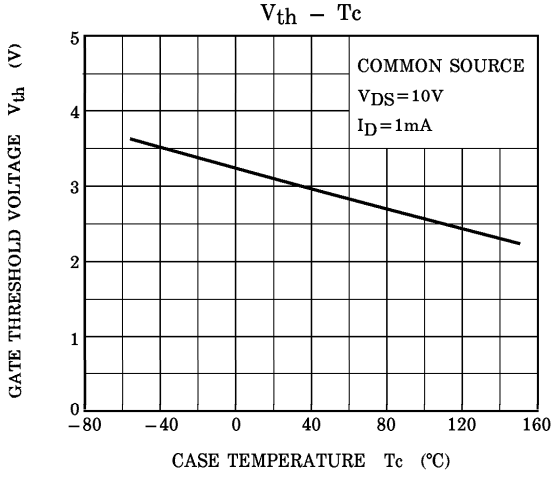
I_{DR} – V_{DS}



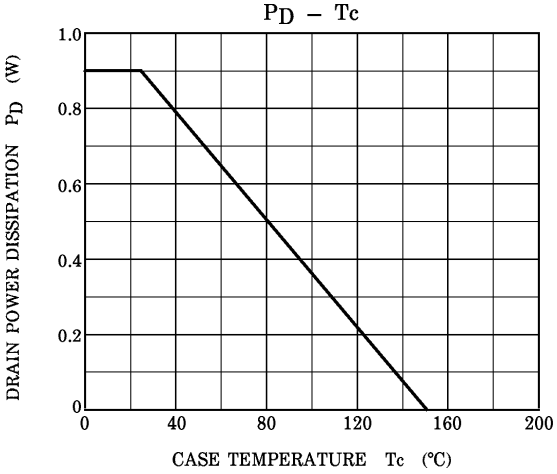
CAPACITANCE – V_{DS}



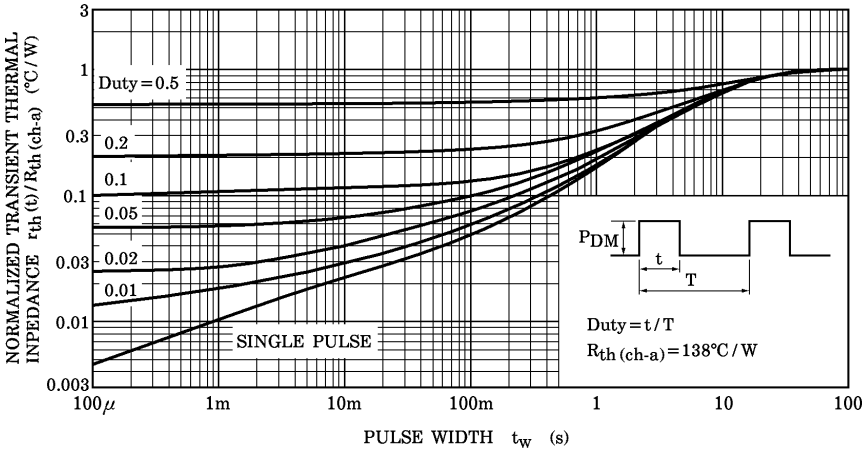
V_{th} – Tc



P_D – Tc



r_{th} – t_w



SAFE OPERATING AREA